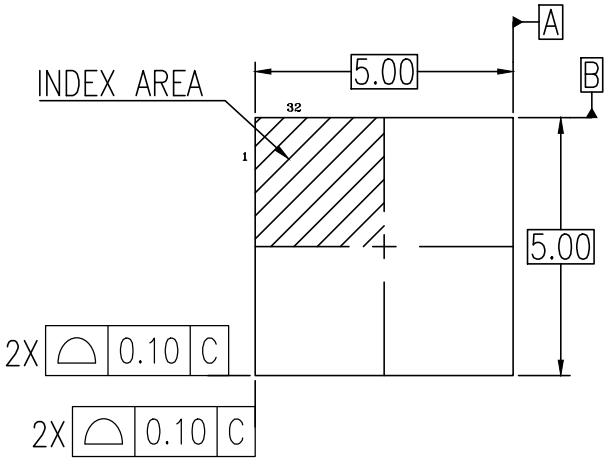
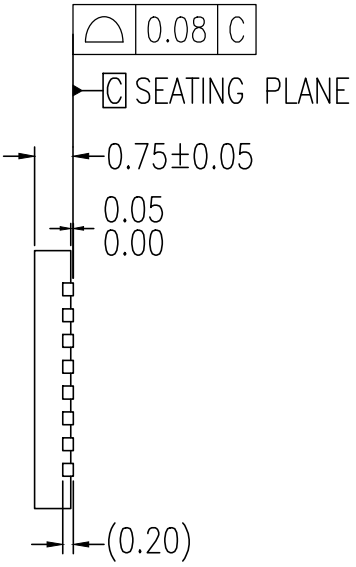
32-VFQFPN, Package Outline Drawing

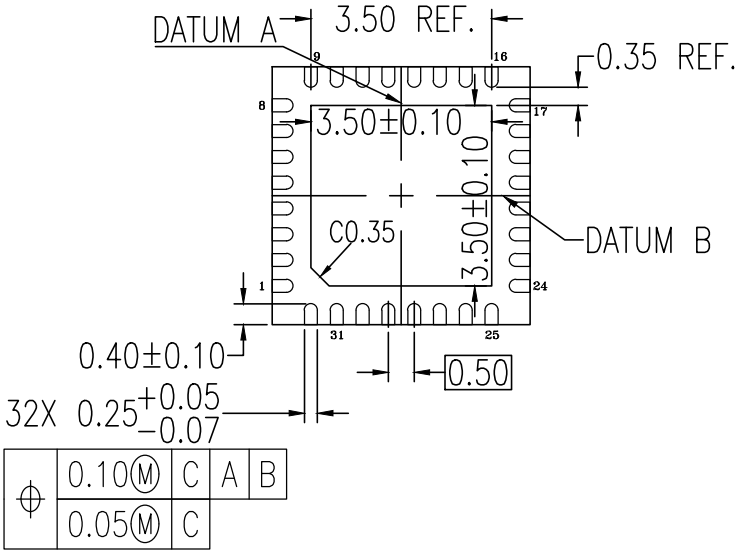
5.00 x 5.00 x 0.75 mm Body, 3.50 x 3.50 mm Epad, 0.5mm Pitch



TOP VIEW



SIDE VIEW

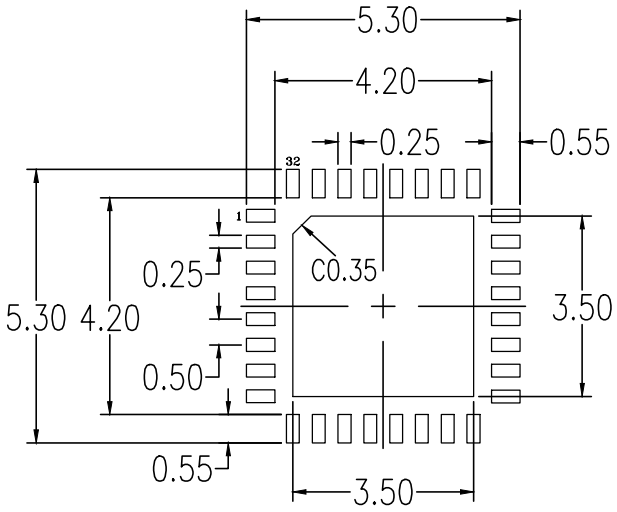


BOTTOM VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5−2009
2. ALL DIMENSIONS ARE IN MILLIMETERS

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RECOMMENDED LAND PATTERN DIMENSION

NOTES:
1. ALL DIMENSIONS ARE IN MM. ANGLES IN DEGREES
2. TOP DOWN VIEW. AS VIEWED ON PCB
3. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN
4. NSMD PATTERN ASSUMED

Package Revision History		
Date Created	Rev No.	Description
Sep. 20, 2019	00	Initial Release
June 22, 2021	01	Update to Renesas Logo

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